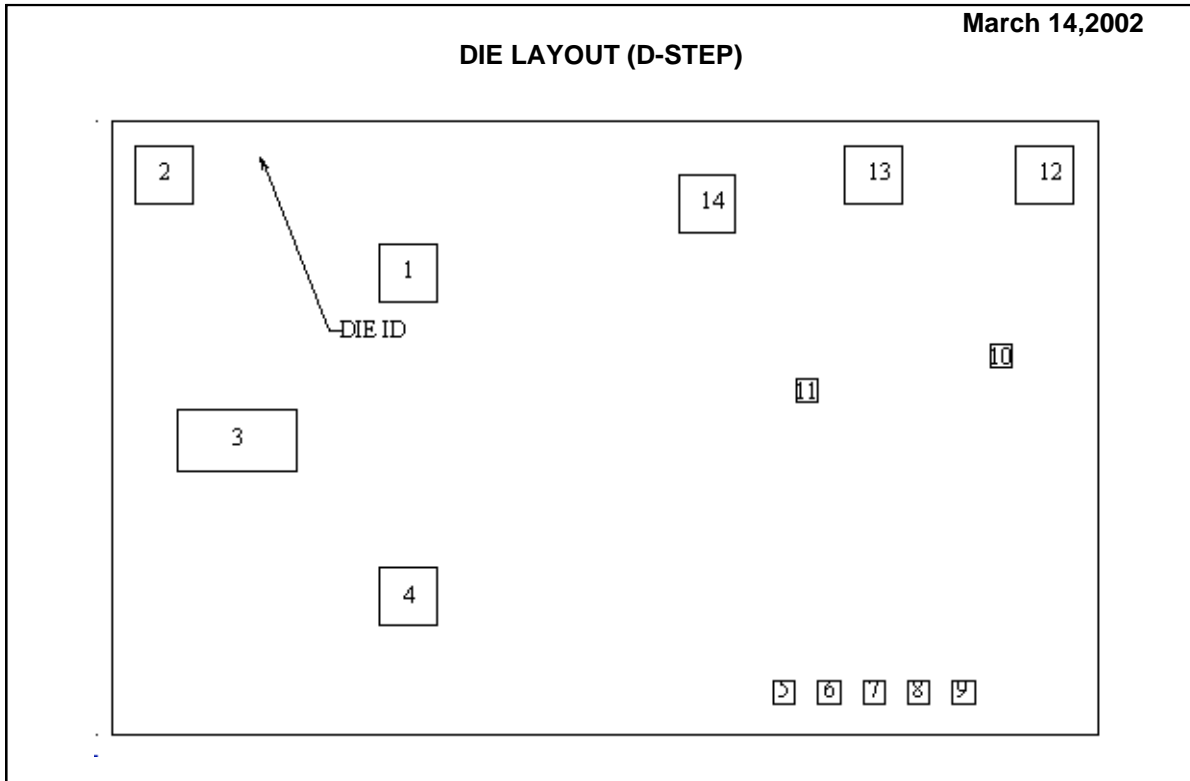


**LM2991 MD8 MW8  
NEGATIVE LOW DROPOUT ADJUSTABLE REGULATOR**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LM2991D	Bond Pad Opening Size (min)	190µm x 190µm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	3277µm x 2032µm 129mils x 80mils	Back Side Connection	INPUT
Thickness	254µm Nominal		
Min Pitch	148µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (D -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL	PAD#	X/Y CORRDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INPUT	1	-652	513	190	x	190
OUTPUT	2	-1463	840	190	x	190
OUTPUT	3	-1222	-42	400	x	200
INPUT	4	-652	-560	190	x	190
NC	5	594	-877	75	x	75
NC	6	745	-877	75	x	75
NC	7	893	-877	75	x	75
NC	8	1041	-877	75	x	75
NC	9	1189	-877	75	x	75
NC	10	1315	239	75	x	75
NC	11	670	126	75	x	75
ADJ	12	1461	840	190	x	190
ON/OFF	13	891	840	190	x	190
GND	14	339	746	190	x	190

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